

**Features:**

- Isolated mounting base 3000V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving

**Typical Applications**

- AC/DC Motor drives
- Various rectifiers
- DC supply for PWM inverter

<b>V<sub>RRM</sub>, V<sub>DRM</sub></b>	<b>Type &amp; Outline</b>		
2000V	MTx250-20-413F3D	MFx250-20-413F3D	
2200V	MTx250-22-413F3D	MFx250-22-413F3D	
2500V	MTx250-25-413F3D	MFx250-25-413F3D	
2500V	MT250-25-413F3DG		

MTx stands for any type of **MTC, MTA, MTK**MFx stands for any type of **MFC, MFA, MFK**

<b>SYMBOL</b>	<b>CHARACTERISTIC</b>	<b>TEST CONDITIONS</b>	<b>T<sub>j</sub>(°C)</b>	<b>VALUE</b>			<b>UNIT</b>
				<b>Min</b>	<b>Type</b>	<b>Max</b>	
I <sub>T(AV)</sub>	Mean on-state current	180° half sine wave 50Hz Single side cooled, T <sub>c</sub> =85°C	125			250	A
I <sub>T(RMS)</sub>	RMS on-state current					392	A
I <sub>DRM</sub> I <sub>RRM</sub>	Repetitive peak current	at V <sub>DRM</sub> at V <sub>RRM</sub>	125			30	mA
I <sub>TSM</sub>	Surge on-state current	V <sub>R</sub> =60%V <sub>RRM</sub> , t=10ms half sine,	125			6.8	kA
I <sup>2</sup> t	I <sup>2</sup> t for fusing coordination					231	10 <sup>3</sup> A <sup>2</sup> s
V <sub>TO</sub>	Threshold voltage		125			0.85	V
r <sub>T</sub>	On-state slope resistance					0.80	mΩ
V <sub>TM</sub>	Peak on-state voltage	I <sub>TM</sub> =750A	25			1.73	V
dV/dt	Critical rate of rise of off-state voltage	V <sub>DM</sub> =67%V <sub>DRM</sub>	125			1000	V/μs
dI/dt	Critical rate of rise of on-state current	Gate source 1.5A t <sub>r</sub> ≤0.5μs Repetitive	125			200	A/μs
I <sub>GT</sub>	Gate trigger current	V <sub>A</sub> =12V, I <sub>A</sub> =1A	25	30		180	mA
V <sub>GT</sub>	Gate trigger voltage			0.7		2.5	V
I <sub>H</sub>	Holding current			10		200	mA
I <sub>L</sub>	Latching current					1000	mA
V <sub>GD</sub>	Non-trigger gate voltage	V <sub>DM</sub> =67%V <sub>DRM</sub>	125			0.20	V
R <sub>th(j-c)</sub>	Thermal resistance Junction to case	Single side cooled per chip				0.12	°C/W
R <sub>th(c-h)</sub>	Thermal resistance case to heatsink	Single side cooled per chip				0.04	°C/W
V <sub>iso</sub>	Isolation voltage	50Hz, R.M.S, t=1min, I <sub>iso</sub> :1mA(MAX)		3000			V
F <sub>m</sub>	Terminal connection torque(M8)			10		12	N·m
	Mounting torque(M6)			4.5		6.0	N·m
T <sub>vj</sub>	Junction temperature			-40		125	°C
T <sub>stg</sub>	Stored temperature			-40		125	°C
W <sub>t</sub>	Weight				770		g
<b>Outline</b>	413F3D						

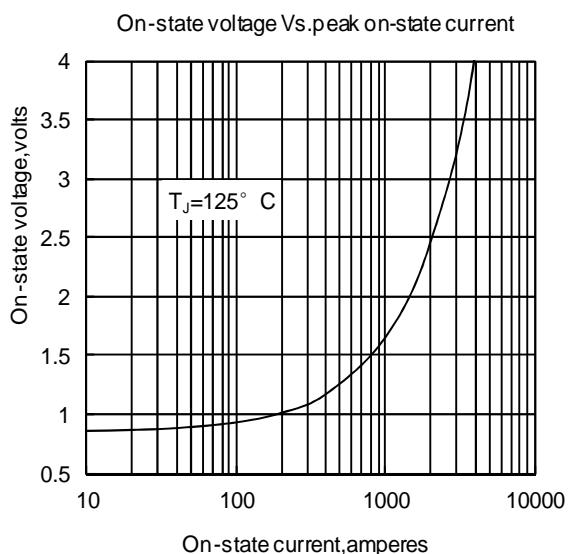


Fig. 1

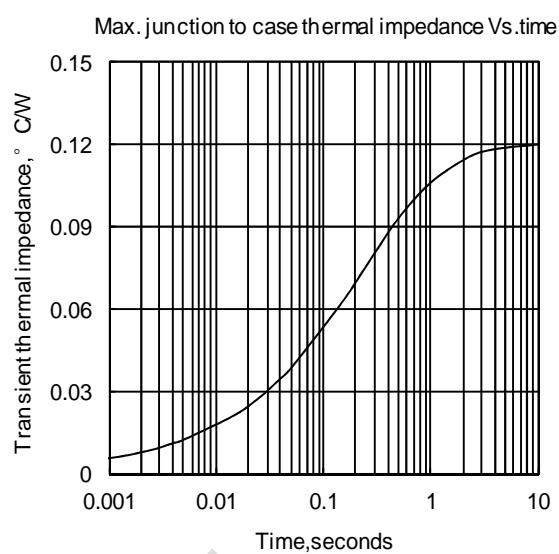


Fig. 2

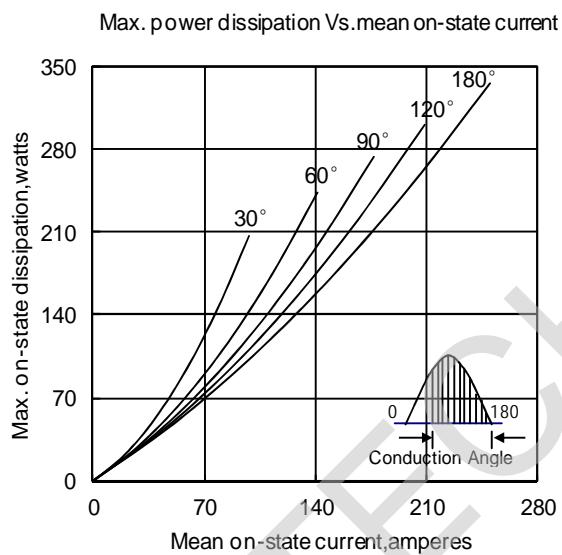


Fig. 3

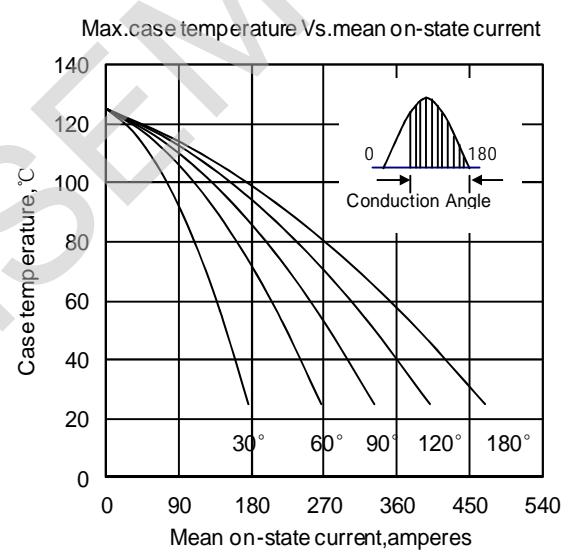


Fig. 4

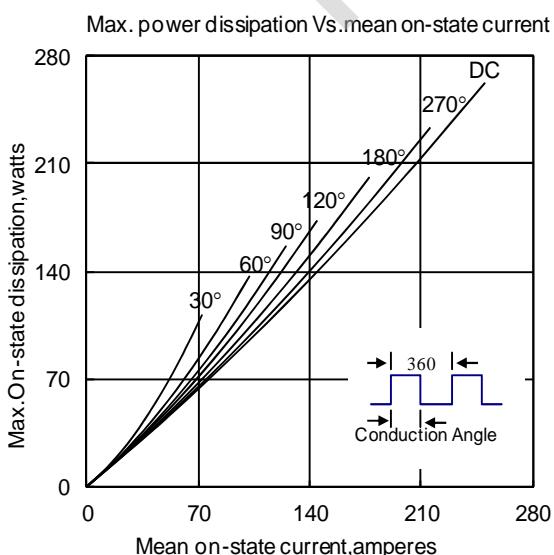


Fig. 5

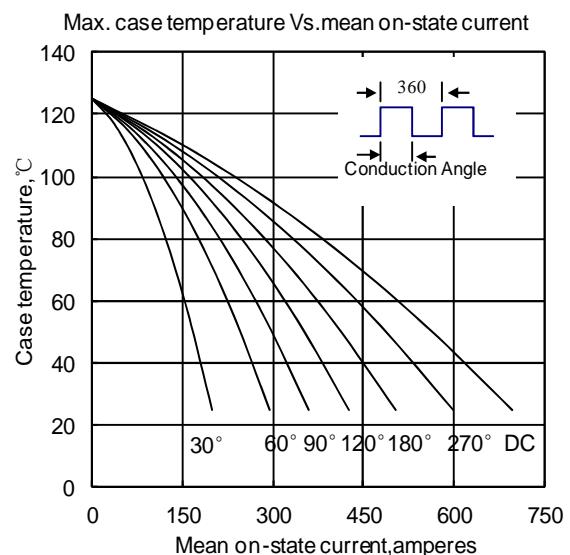


Fig. 6

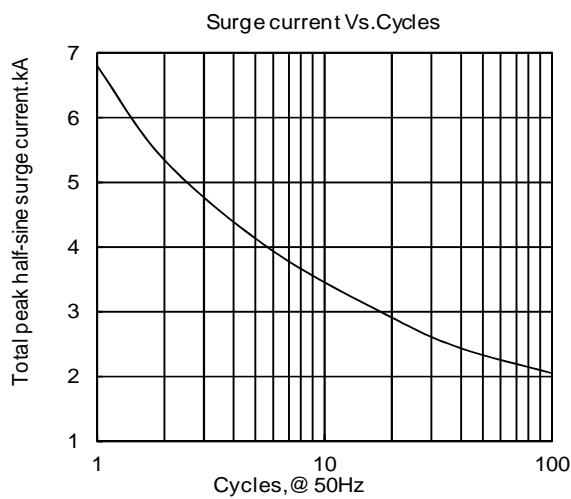


Fig. 7

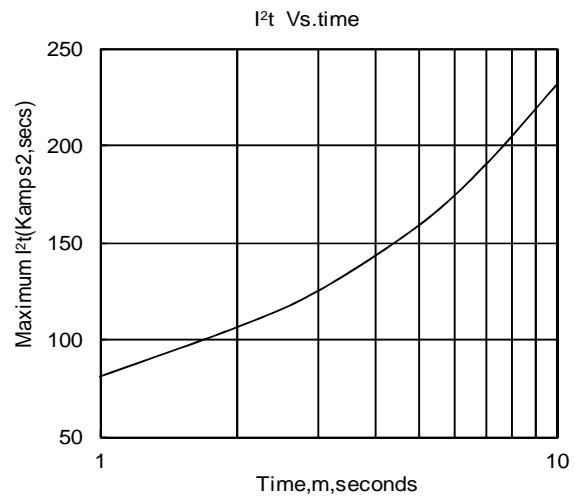


Fig. 8

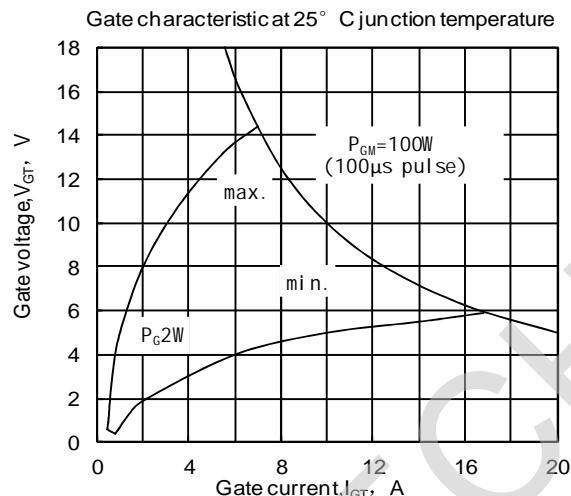


Fig. 9

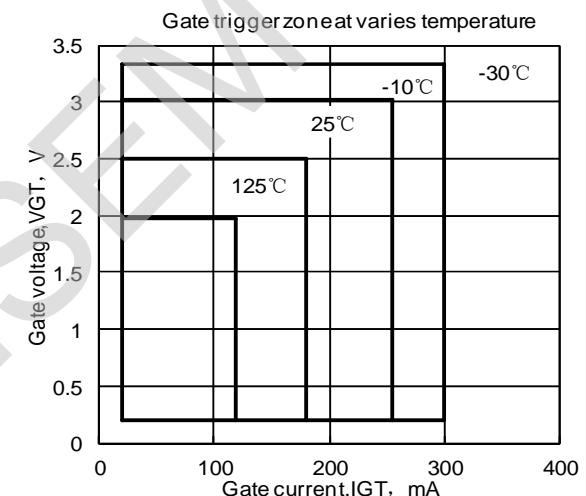
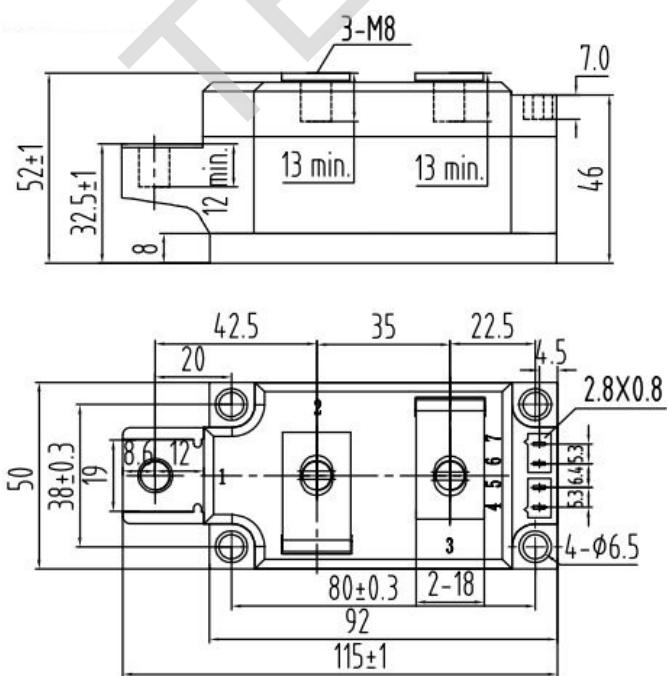


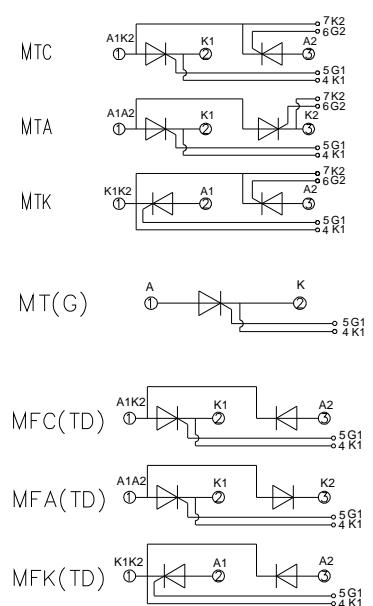
Fig. 10

**Outline:****Unmarked dimensional tolerance: ±0.5mm**

TECHSEM reserves the right to change specifications without notice.

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